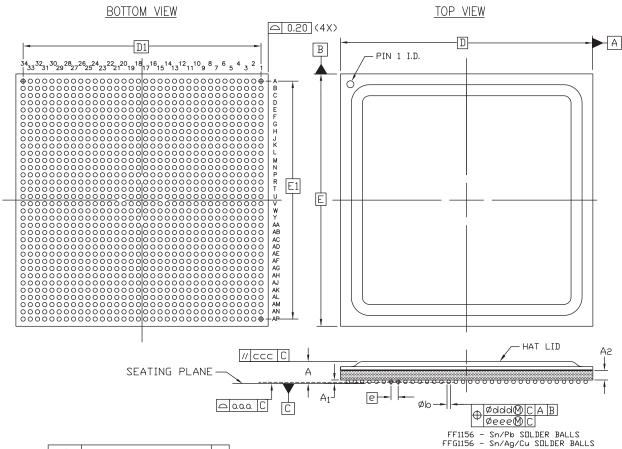


PK384 (v1.1) December 14, 2009

## 1156 Ball Flip-Chip BGA (FF1156/FFG1156) Package for Virtex-5 FPGAs



S Y M B	MILLIMETERS			N I T F
L	MIN.	N□M.	MAX.	Ė
Α	2.70	*	3.50	
A <sub>1</sub>	0.40	0.50	0.60	
Α <sub>2</sub>	0.90	*	1.50	
D/E	35.00 BASIC			
D1/E1	33.00 REF			
е	1.00 BASIC			
Øb	0.50	0.60	0.70	
aaa	*	*	0.20	
ccc	*	*	0.35	
ddd	4	*	0,25	
eee	*	~	0.10	
М	34			2

## NOTES:

- 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
- 2. SYMBOL 'M' IS THE BALL MATRIX SIZE
- 3. CONFORMS TO JEDEC MS-034-AAR-1
- 4. THIS PACKAGE IS ONLY USED FOR VIRTEX®-5 FPGAS REFER TO PK401 FOR THE MECHANICAL DRAWING OF THE FF1156 PACKAGE USED BY VIRTEX-6 FPGAS

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions	
06/04/09	1.0	Initial Xilinx release.	
12/14/09	1.1	Revised document title and added note 4 to indicate this package is a variation of the FF1156/FFG1156 type used only on Virtex-5 FPGAs.	

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